

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

Claim 1. (currently amended):      A semiconductor device comprising:  
  
an organic insulating film having an opening,  
  
wherein said organic insulating film has an insulated modified portion in a side of said opening, and  
  
said modified portion includes nitrogen atoms and carbon atoms forming carbon-nitrogen bonds.

Claim 2. (previously presented):      The semiconductor device according to claim 1,  
  
wherein said modified portion further comprises fluorine atoms, and  
  
a concentration of said fluorine atoms in said modified portion is lower than a concentration of said nitrogen atoms.

Claim 3. (original):      The semiconductor device according to claim 2, further comprising:  
  
a metal conductor whose main component is copper, formed in said opening.

Claim 4. (previously presented):      The semiconductor device according to claim 3,  
  
wherein said metal conductor is in direct contact with said modified portion.

Claim 5-18 (canceled).

Claim 19. (previously presented): The semiconductor device according to claim 4,  
wherein the metal conductor comprises a barrier film whose main component is tantalum.

Claim 20. (previously presented): The semiconductor device according to claim 19,  
wherein the barrier film is in direct contact with the modified portion.